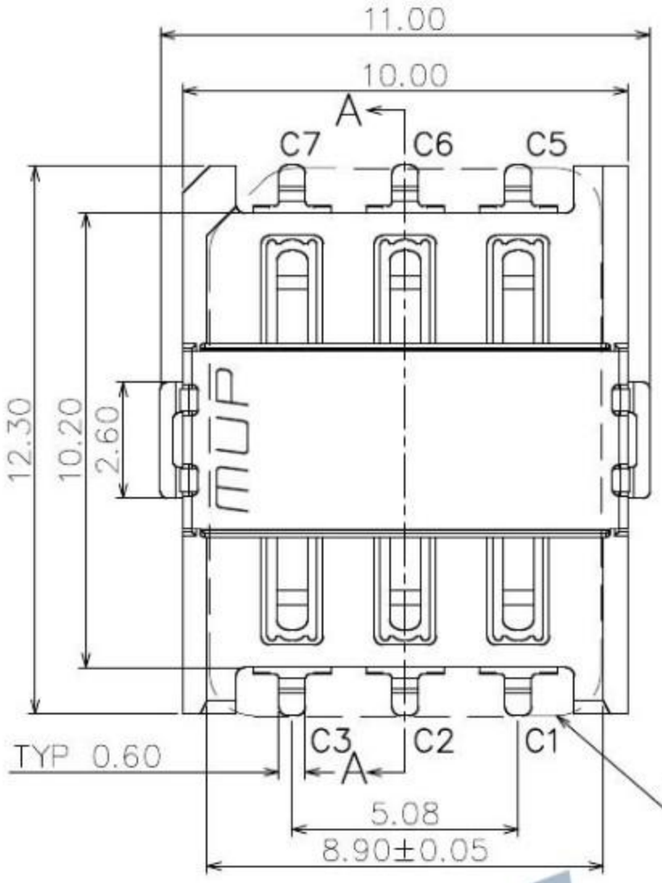
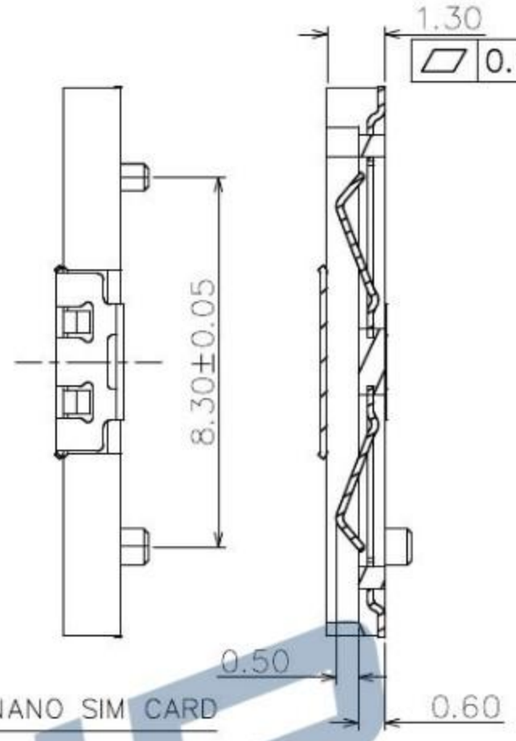
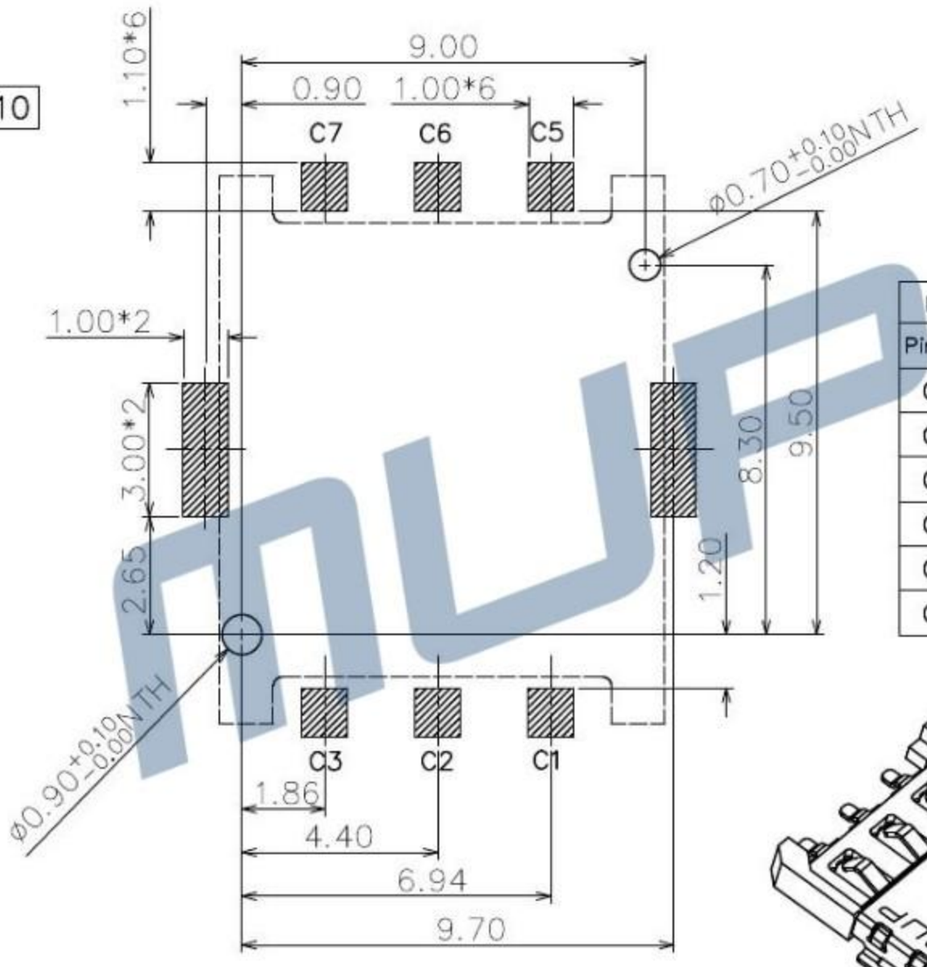
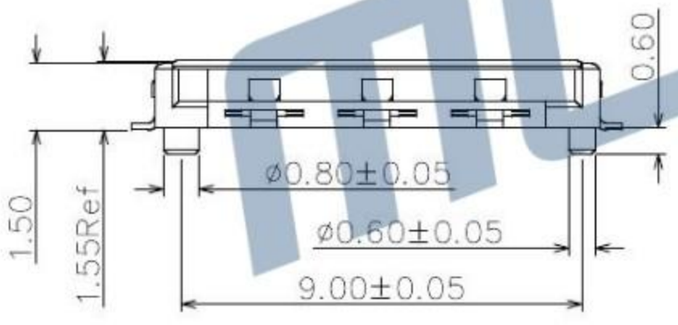
REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Henry Apr.09.2014
X2					







Nano–SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 12.30LX10.00WX1.50H mm

Weight: Approx 0.53±0.2g

Durability: 1,500 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical,100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vaporphase: 215°C,30sec.Max

IR reflow: 250°C,5sec.Max

Manual soldering: 370°C,3sec.Max

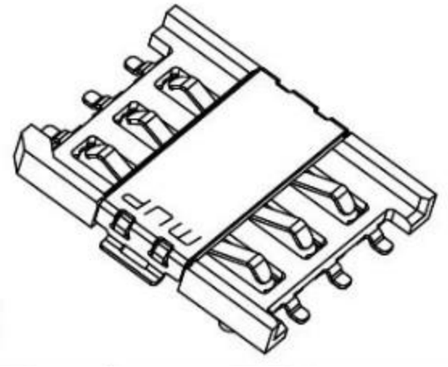
4.Environmental Characteristics

Operating temperature: −40°C~+85°C

Operating humidity: 10%~+95%RH

RECOMMENDED P.C.B LAYOUT

COMPONENT SIDE(TOLERANCE ±0.05)



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi–temp Thermoplastic	Black UL94V–0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	SMT area:Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X°	±5°
X.X	±0.25	X.X°	±4°
X.XX	±0.15	X.XX°	±3°
X.XXX	±0.10	X.XXX°	±2°

PROJ. UNIT mm SCALE 1:1

CUSTOMER DRAWING

MUP® MUP INDUSTRIAL CO.,LTD.

NAME: **Nano-SIM Card Connector**

MODEL NO: **MUP-C781-1**

TYPE : **H1.50mm 6 PIN**

DRAWN	Henry Apr.09.2014	DWG NO.:	DWG–MUP–C781–1
CHECKED	Henry Apr.09.2014	SHEET 1/1	REVISION X1
APPROVAL	Simon Apr.09.2014		